

Patent Abstracts of Japan

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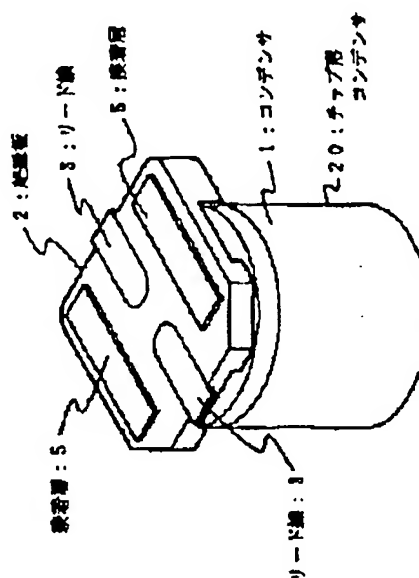
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TITLE : CHIP TYPE CAPACITOR AND
MOUNTING METHOD THEREOF



ABSTRACT : PURPOSE: To realize the surface mounting operation of the title capacitor on a printed board and to solidify its connecting state without changing the structure of an ordinary capacitor.

CONSTITUTION: Through holes 4 into which lead wires 3 are inserted are provided; an insulating plate 2 provided with bonding layers 5, in parts of the bottom face, which are composed mainly of a thermoplastic resin are arranged at the edge of a capacitor 1; and the lead wires 3 which have been inserted into the through holes 4 in the insulating plate 2 are bent along the bottom face of the insulating plate 2. A chip type capacitor 20 is mounted on a printed board 10; this assembly is heat-treated and, after that, cooled; and the capacitor is fixed and bonded to the printed board 10. Thereby, it is possible to prevent the chip type capacitor 20 from rising.

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